



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Shunpei Yamazaki, et al. Art Unit : 1765
Serial No. : 09/892,225 Examiner : Mathew J. Song
Filed : June 25, 2001
Title : SEMICONDUCTOR DEVICE AND FABRICATION METHOD THEREFOR

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

INFORMATION DISCLOSURE STATEMENT

Applicant submits the reference listed on the attached form PTO-1449. In the IDS mailed on May 27, 2003, applicant erroneously cited reference US2003-0001098A1. Reference US2003-0001098A1 should be replaced by the attached reference US2003-0010980A1.

This filing is being made with the filing of a Request for Continued Examination. No fee is required.

Respectfully submitted,

Date: 1/23/04



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Substitute Form PTO-1449
(Modified)U.S. Department of Commerce
Patent and Trademark OfficeAttorney's Docket No.
07977-279001Application No.
09/892,225**Information Disclosure Statement
by Applicant**

(Use several sheets if necessary)

(37 CFR §1.98(b))

Applicant
Shunpei Yamazaki, et al.Filing Date
June 25, 2001Group Art Unit
1765**U.S. Patent Documents**

Examiner Initial	Desig. ID	Document Number	Publication Date	Patentee	Class	Subclass	Filing Date If Appropriate
	AA	2003-0010980	01/16/2003	Yamazaki et al.			
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

Foreign Patent Documents or Published Foreign Patent Applications

Examiner Initial	Desig. ID	Document Number	Publication Date	Country or Patent Office	Class	Subclass	Translation	
							Yes	No
	AL							
	AM							
	AN							
	AO							
	AP							

Other Documents (include Author, Title, Date, and Place of Publication)

Examiner Initial	Desig. ID	Document
	AQ	
	AR	
	AS	
	AT	

Examiner Signature

Date Considered

EXAMINER: Initials citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.